



Bill of Materials

TI DESIGNS

ITEM	QTY	REFERENCE DESIGNATOR	VALUE	DESCRPTION	SIZE	MANUFACTURER	MANUFACTURER PART NUMBER
1	4	C1,C7,C11,C12	0.1uF	CAP .1UF 25V CERAMIC X7R 0603	603	Panasonic	ECJ-1VB1E104K
2	1	C2	47uF	CAP ALUM 47UF 10V 20% SMD	APXE100ARA470ME61G	United Chemi Con	APXE100ARA470ME61G
3	1	C3	10uF	CAP CER 10UF 25V Y5V 1206	1206	Taiyo-Yuden	TMK316F106ZL-T
4	1	C4	10000pF	CAP CER 10000PF 10V 10% X5R 0402	402	Murata	GRM155R61A103KA01D
5	1	C5	10pF	CAP CER 10PF 50V 5% NPO 0402	402	Yageo	CC0402JRNPO9BN100
6	1	C6	6200pF	CAP CER 6200PF 50V 5% NPO 0603	603	Kemet	C0603C622J5GAC7867
7	3	C8,C9,C10	1uF	CAP CER 1UF 25V 10% X5R 0603	603	Taiyo-Yuden	TMK107BJ105KA-T
8	1	D1	B130-13-F	DIODE SCHOTTKY 30V 1A SMA	SMA	Diodes Inc.	B130-13-F
9	1	H1	68000-103HLF	BERGSTIK II .100" SR STRAIGHT	SIP-3	FCI	68000-103HLF
10	1	J1	929834-01-06-RK	CONN HEADER 6POS SNGL .100 STR	929834-01-06-RK	3M	929834-01-06-RK
11	1	J2	929834-01-04-RK	CONN HEADER 4POS SNGL .100 STR	929834-01-04-RK	3M	929834-01-04-RK
12	1	J3	S2B-EH	CONN HEADER EH SIDE 2POS 2.5MM	S2B-EH	JST	S2B-EH(LF)(SN)
13	1	L1	10uH	Fixed Inductors Power Inductor 10 uH 20 % 4.9 A	XAL5050-103MEB	CoilCraft	XAL5050-103MEB
14	1	R1	52.3K	RES 52.3K OHM 1/10W 1% 0402 SMD	402	Panasonic	ERJ-2RKF5232X
15	4	R2,R3,R5,R6	10.0K	RES 10.0K OHM 1/16W 1% 0402 SMD	402	Vishay Dale	CRCW040210K0FKED
16	1	R4	31.6K	RES 31.6K OHM 1/16W 1% 0402 SMD	402	Vishay Dale	CRCW040231K6FKED
17	1	R7	30K	RES 30K OHM 1/10W 1% 0402 SMD	402	Panasonic	ERJ-2RKF3002X
18	1	R9	4.7	RES 4.7 OHM 1/10W 5% 0402 SMD	402	Panasonic	ERJ-2GEJ4R7X
19	1	R10	0.1	RES 0.1 OHM 1/5W 1% 0603 SMD	603	Panasonic	ERJ-L03KF10CV
20	1	U1	TPS54232	IC REG BUCK ADJ 2A 8SOIC	8SOIC	Texas Instruments	TPS54232D
21	1	U2	REF5050	IC VREF SERIES PREC 5V 8-SOIC	8SOIC	Texas Instruments	REF5050AQDRQ1
22	1	U3	OPA569	IC OPAMP GP 1.2MHZ RRO 20SOPWR	20SOPWR	Texas Instruments	OPA569AIDWPR
23	1	U4	INA213	IC OPAMP CURR SENSE 14KHZ SC70-6	SC70-6	Texas Instruments	INA213BIDCKR

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